What is claimed is:

1. An inspecting method for inspecting an influence of an installation environment upon a processing apparatus including a chuck table for holding a workpiece, a processing unit processing said workpiece held on said chuck table, a moving mechanism for relatively moving said chuck table and said processing unit, and an imaging unit fixed to said processing unit to image said workpiece held on said chuck table, said inspecting method comprising:

a mark setting step of setting a mark for specifying a relative positional relation between said chuck table and said processing unit;

an imaging step of imaging said mark plural times, thereby creating a plurality of images of said mark, by using said imaging unit in the condition where said moving mechanism is at rest; and

a determining step of detecting a change in a position of said mark across time from said plurality of images obtained by said imaging step and then determining whether or not the influence of said installation environment upon said processing apparatus is present;

said determining step being performed in such a manner that when the amount of change in position of said mark is less than

a threshold, it is determined that the relative positional relation between said chuck table and said processing unit is not influenced by said installation environment,

whereas when the amount of change in position of said mark is greater than or equal to said threshold, it is determined that the relative positional relation between said chuck table and said processing unit is influenced by said installation environment,

wherein said imaging unit and said processing unit are both fixed to a movable plate that is configured and arranged to be moved, with respect to said chuck table, in at least one direction, and

wherein said processing unit comprises a laser processing unit for applying a laser beam to said workpiece.

2. The inspecting method according to claim 1, wherein said imaging step includes setting a distance between said imaging unit and said chuck table so that said imaging unit focuses on said mark, and next starting to image said mark.

3. The inspecting method according to claim 1, wherein said mark is set on said chuck table or on an object held on said chuck table.

4. The inspecting method according to claim 1, wherein said threshold is previously set on the basis of a change in position of said mark at a time when there is no change in said position of said mark due to an external environment.

5. The inspecting method according to claim 1, wherein said determining step further comprises defining a temporary origin and temporary coordinate system in a plane parallel to said surface of said chuck table, and wherein the position of the mark in each of the plurality of images is plotted on said temporary coordinate system, establishing a set of points.

6. The inspecting method according to claim 5, wherein said determining step further comprises calculating an average point from said set of points.

7. The inspecting method according to claim 6, wherein said determining step further comprises establishing a second coordinate system, said second coordinate system having a second origin defined by said average point.

8. The inspecting method according to claim 7, wherein said change in the position of the mark is defined as the distance

between said second origin and the position of the mark having the greatest distance from said second origin.

9. The inspecting method according to claim 7, wherein said change in the position of the mark is defined as the standard deviation of a set, said set comprising the distances between each point in said set of points and said second origin.

10. The inspecting method according to claim 1, wherein said determining step further comprises plotting the change in the position of the mark against a time axis.

11. The inspecting method according to claim 10, wherein said plot is compared to waveforms of known vibrations in the installation environment.

12. The inspecting method according to claim 10, wherein said plot is compared to waveforms of known vibrations in the processing apparatus.

13. The inspecting method according to claim 1, wherein said mark is set on said chuck table.

14. The inspecting method according to claim 1, wherein said mark is set on an object held on said chuck table.

15. The inspecting method according to claim 1, wherein said mark is set on said workpiece.

16. The inspecting method according to claim 1, wherein said determining step includes comparing the sharpness of outlines of the plurality of images of said mark.

17. The inspecting method according to claim 1, wherein said imaging unit and said processing unit are in a fixed relationship to each other, such that when said processing unit is vibrated, said imaging unit is also vibrated.

18. An inspecting method for inspecting an influence of an installation environment upon a processing apparatus including a chuck table for holding a workpiece, a processing unit processing said workpiece held on said chuck table, a moving mechanism for relatively moving said chuck table and said processing unit, and an imaging unit fixed to said processing unit to image said workpiece held on said chuck table, said inspecting method comprising:

a mark setting step of setting a mark for specifying a relative positional relation between said chuck table and said processing unit;

an imaging step of imaging said mark plural times, thereby creating a plurality of images of said mark, by using said imaging unit in the condition where said moving mechanism is at rest; and

a determining step of detecting a change in a position of said mark across time from said plurality of images obtained by said imaging step and then determining whether or not the influence of said installation environment upon said processing apparatus is present;

said determining step being performed in such a manner that when the amount of change in position of said mark is less than a threshold, it is determined that the relative positional relation between said chuck table and said processing unit is not influenced by said installation environment, whereas when the amount of change in position of said mark is greater than or equal to said threshold, it is determined that the relative positional relation between said chuck table and said processing unit is influenced by said installation environment,

wherein said imaging unit and said processing unit are both fixed to a movable plate that is configured and arranged

to be moved, with respect to said chuck table, in at least one direction, and

wherein said processing unit comprises a cutting unit including a rotatable cutting blade.

19. The inspecting method according to claim 18, wherein said imaging step includes setting a distance between said imaging unit and said chuck table so that said imaging unit focuses on said mark, and next starting to image said mark.

20. The inspecting method according to claim 18, wherein said mark is set on said chuck table or on an object held on said chuck table.

21. The inspecting method according to claim 18, wherein said determining step further comprises plotting the change in the position of the mark against a time axis.

22. The inspecting method according to claim 18, wherein said imaging unit and said processing unit are in a fixed relationship to each other, such that when said processing unit is vibrated, said imaging unit is also vibrated.